

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

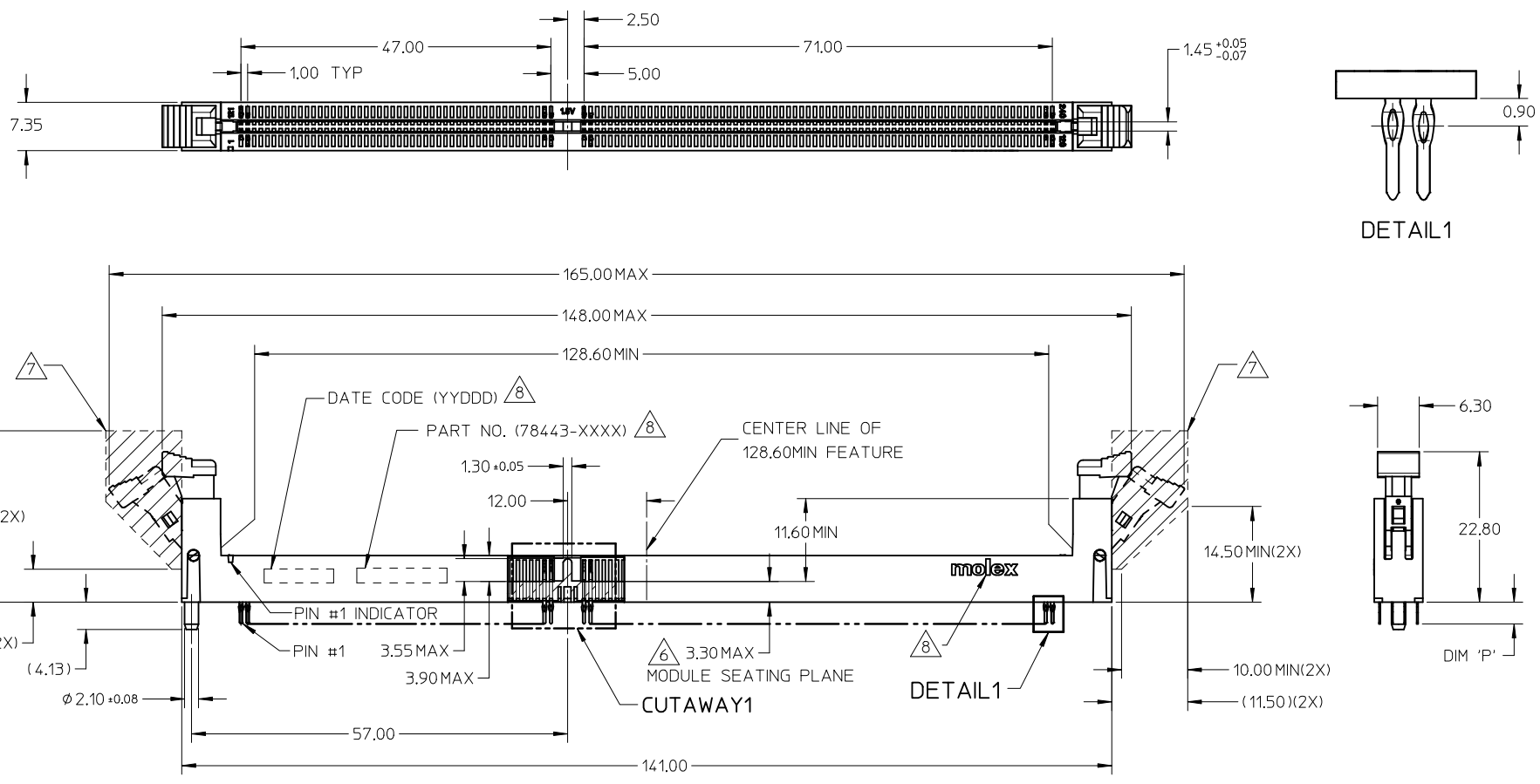
C

B

B

A

A



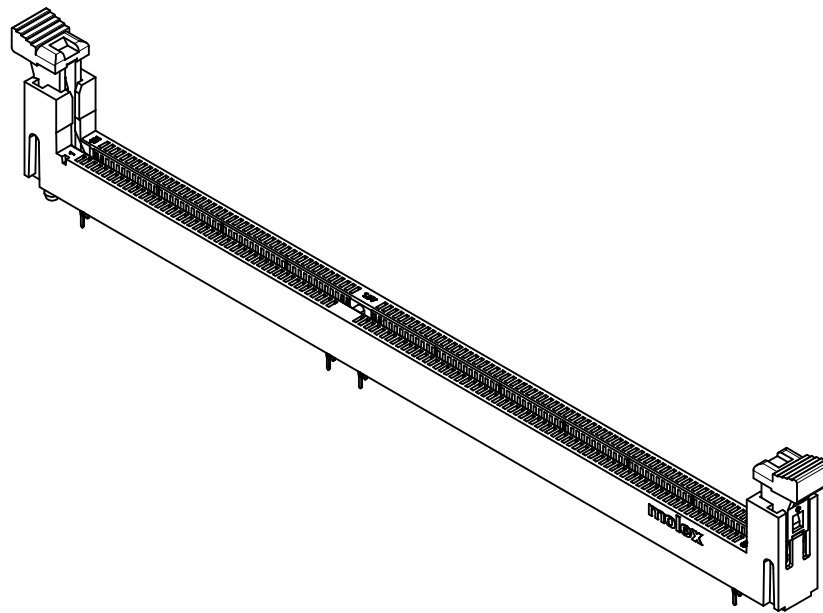
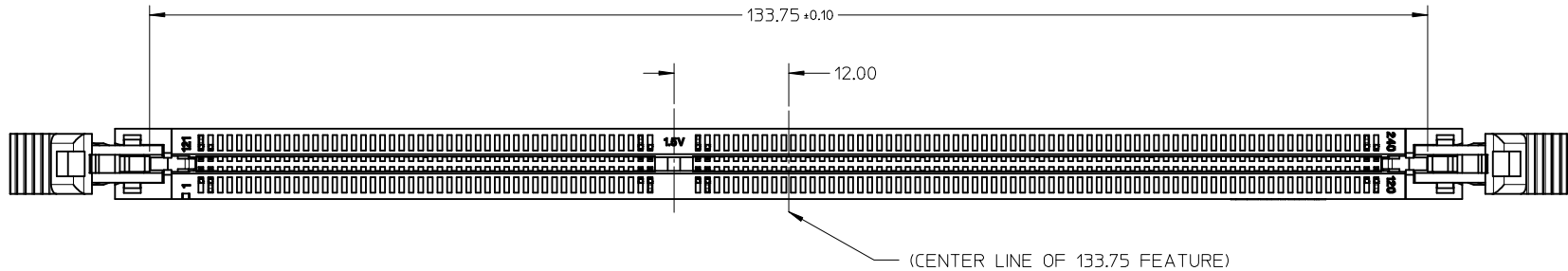
- NOTES:
1. MATERIALS
HOUSING - POLYAMIDE (PA), GLASS FILLED, UL 94V-0, COLOUR - SEE TABLE.
LATCH - POLYIMIDE (PA), COLOUR - SEE TABLE.
- POLYSULFONE, UL 94HB - CLEAR.
TERMINAL - COPPER ALLOY.
 2. PLATING - SEE TABLE.
 3. PRODUCT SPECIFICATION: SEE TABLE.
 4. PRODUCT SHALL BE PACKED IN TRAY.
 5. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS.
(MEASURED FROM P.C.PADS).

6. MODULE SEATING PLANE FROM TOP OF PCB.
7. KEEP OUT ZONE RESERVED FOR LATCH.
8. MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.

REMOVE PART NO. EC NO: S2014-1201 DRWN:CGTAN 2014/04/22 CHKD:CTEH 2014/06/11 APPR:SHLENI 2014/06/11	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		$F_A=0$ $F_G=0$ $F_P=0$	mm	INCH	MM ONLY	NTS	METRIC		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---	DRAWN BY: CMTEO CHECKED BY: CGTAN APPROVED BY: SHLENI		DATE: 2008/06/19 DATE: 2008/07/25 DATE: 2010/03/29	TITLE: DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-78443-001	SHEET NO. 1 OF 6				

9 8 7 6 5 4 3 2 1

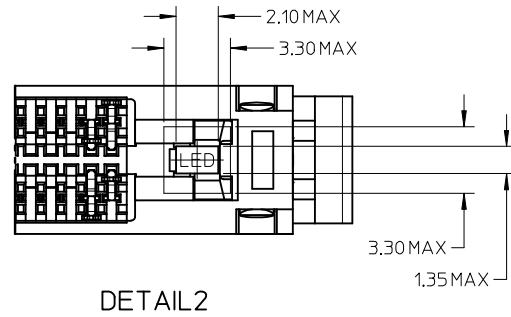
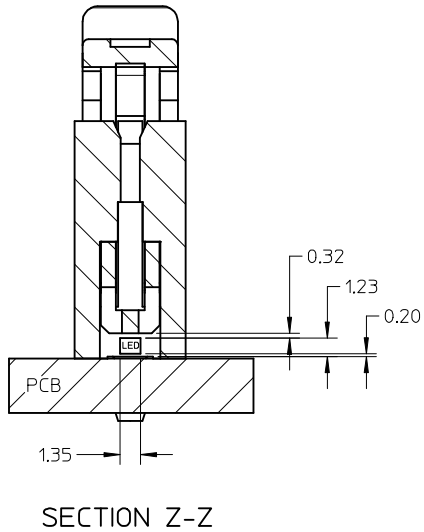
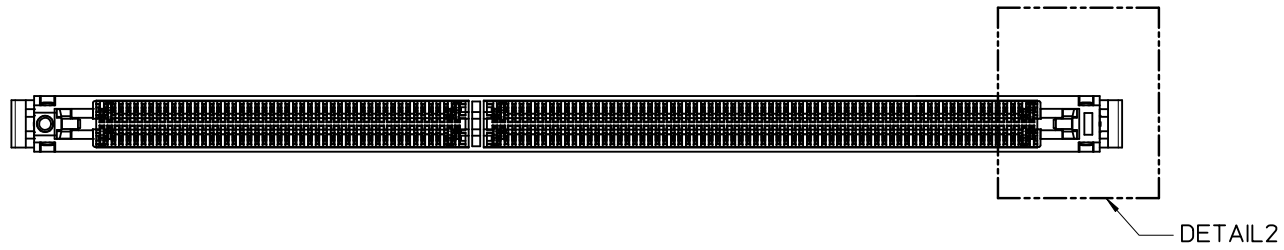
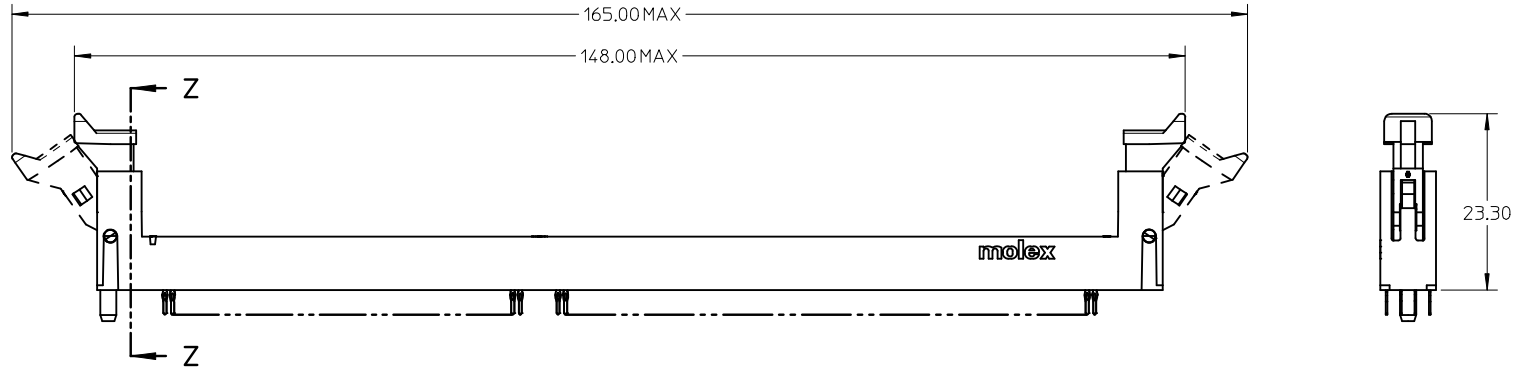
10 9 8 7 6 5 4 3 2 1



REMOVE PART NO. EC NO: S2014-1201 DRWN:CGTAN 2014/04/22 CHKD:CCTEH 2014/06/11 APPR:SHLENI 2014/06/11	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DIMENSION STYLE MM ONLY DRAWN BY: CMTEO DATE: 2008/06/19 CHECKED BY: CGTAN DATE: 2008/07/25 APPROVED BY: SHLENI DATE: 2010/03/29	SCALE: NTS DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.: SEE TABLE SIZE: A3	MOLEX INCORPORATED DOCUMENT NO.: SD-78443-001	SHEET NO.: 2 OF 6	
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	REMOVE PART NO. A2				

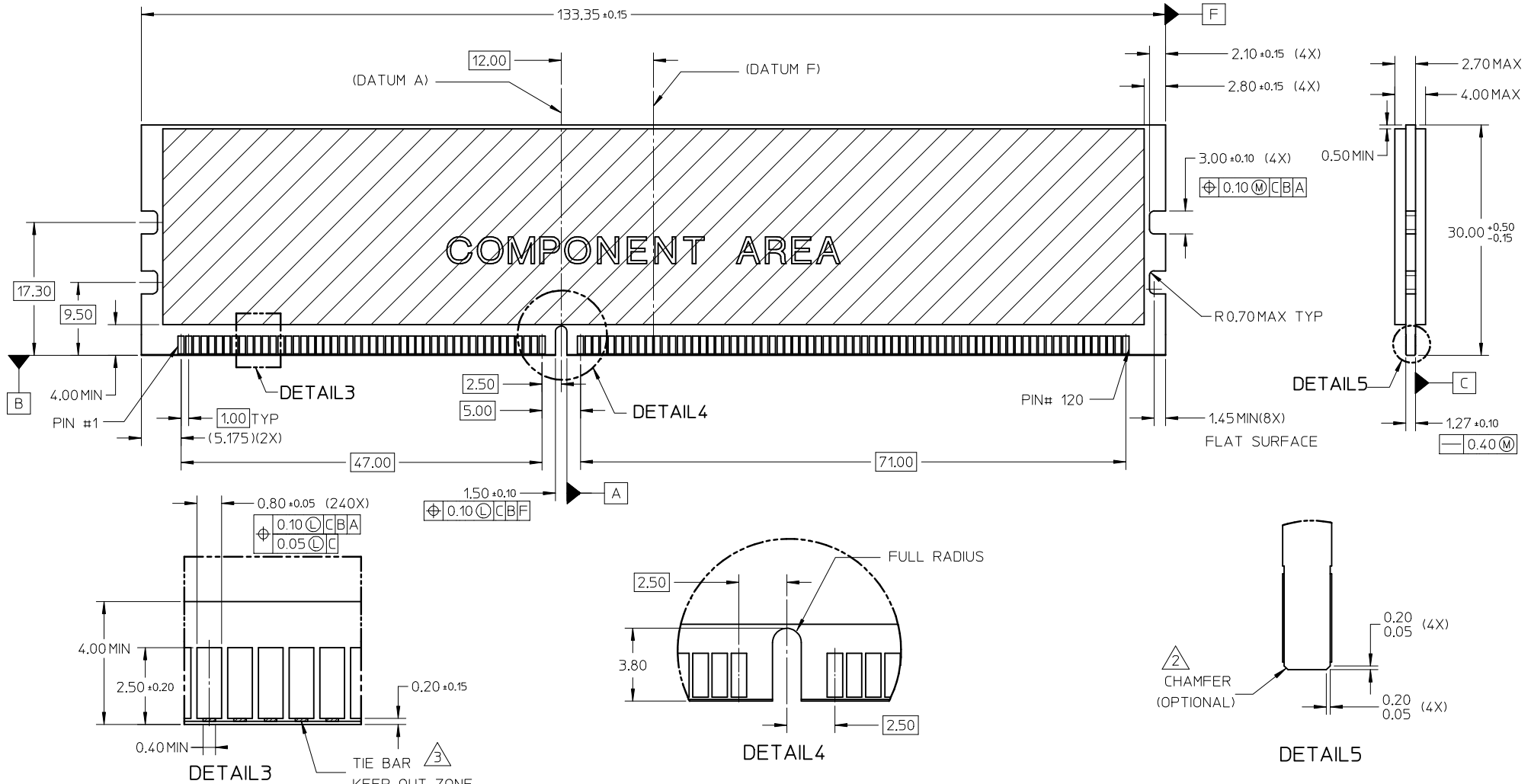
9 8 7 6 5 4 3 2 1

CONNECTOR WITH CLEAR LATCHES



REMOVE PART NO. EC NO: S2014-1201 DRWN:CGTAN 2014/04/22 CHKD:CCTEH 2014/06/11 APPR:SHLENI 2014/06/11	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DIMENSION STYLE MM ONLY DRAWN BY: CMTEO DATE: 2008/06/19 CHECKED BY: CGTAN DATE: 2008/07/25 APPROVED BY: SHLENI DATE: 2010/03/29	SCALE: NTS DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.: SEE TABLE SIZE: A3	MOLEX INCORPORATED DOCUMENT NO.: SD-78443-001	SHEET NO.: 3 OF 6	
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)

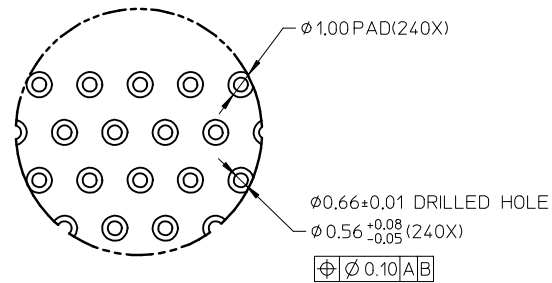
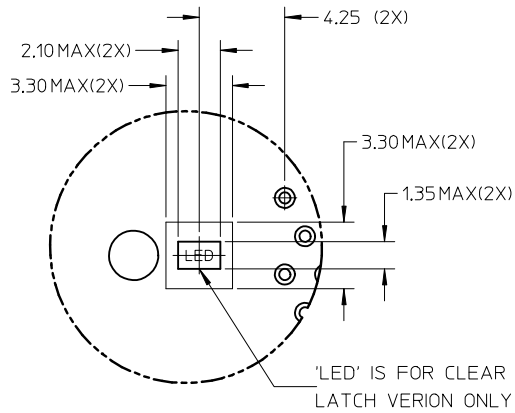
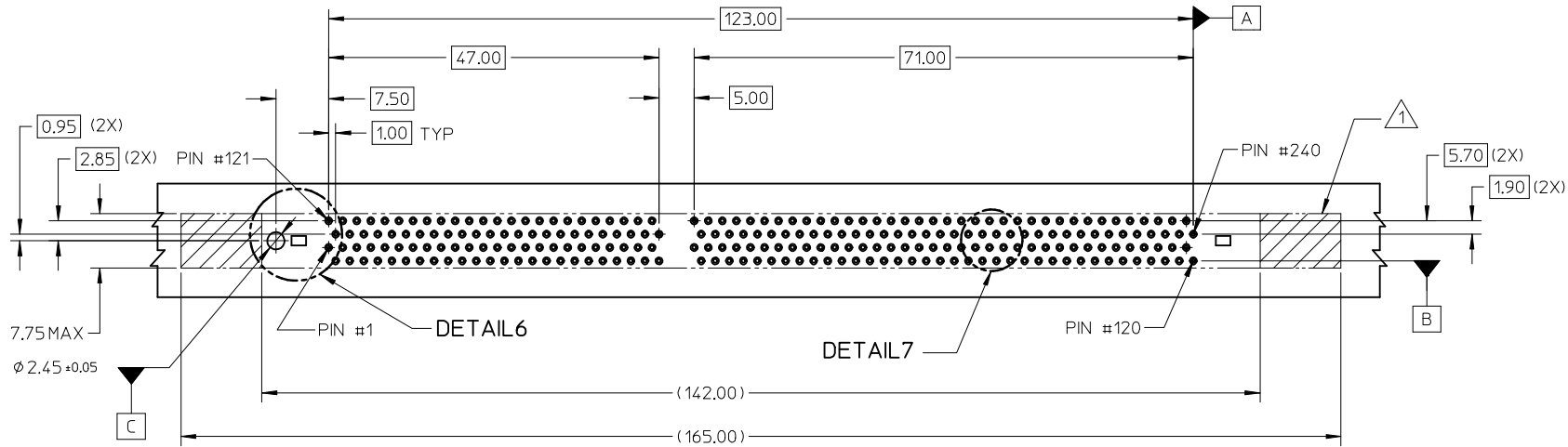


NOTES:

- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
 OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
 OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC
 CONTACT GRADE CORROSIVE BARRIER LUBRICANT
- CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
- LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

REMOVE PART NO. EC NO: S2014-1201 DRWN:CGTAN 2014/04/22 CHKD:CCTEH 2014/06/11 APPR:SHLENI 2014/06/11	QUALITY SYMBOLS F _A =0 F _E =0 F _P =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		mm	INCH	DRAWN BY CMTEO	DATE 2008/06/19	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR				
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY CGTAN	DATE 2008/07/25	MOLEX INCORPORATED				
		2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	APPROVED BY SHLENI	DATE 2010/03/29	DOCUMENT NO. SD-78443-001				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ± 1 °		MATERIAL NO. SEE TABLE		SHEET NO. 4 OF 6		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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DETAIL 6

DETAIL 7

NOTE:

△ KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB.

REMOVE PART NO. EC NO: S2014-1201 DRWN:CGTAN 2014/04/22 CHKD:CCTEH 2014/06/11 APPR:SHLENI 2014/06/11	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1°	DIMENSION STYLE MM ONLY DRAWN BY: CMTEO DATE: 2008/06/19 CHECKED BY: CGTAN DATE: 2008/07/25 APPROVED BY: SHLENI DATE: 2010/03/29	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR					
	MATERIAL NO. SEE TABLE DOCUMENT NO. SD-78443-001					
	SHEET NO. 5 OF 6					

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TIN OPTION

PART NO.	VOLTAGE KEY POS.	VOLTAGE	DIM 'P'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING OPTION	SOLDERTAIL PLATING OPTION	HOUSING COLOUR	LATCH COLOUR	PRODUCT SPECIFICATION
78443-1001	CENTER	1.5V	3.30±0.25	3.60	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	0.38-1.52 MICROMETER/15-60 MICROINCH TIN OVER 1.27MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	BLACK	BLACK	PS-78443-001
78443-1002							NATURAL (OFF-WHITE)	NATURAL (OFF-WHITE)	
78443-0107							BLACK	NATURAL (OFF-WHITE)	

REMOVE PART NO. EC NO: S2014-1201 DRWN:CGTAN 2014/04/22 CHKD:CCTE 2014/06/11 APPR:SHLENI 2014/06/11	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$\nabla_A=0$	mm	INCH	DRAWN BY	DATE	TITLE			
	$\nabla_C=0$	4 PLACES ± ---	± ---	CMTEO	2008/06/19	DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR			
	$\nabla_P=0$	3 PLACES ± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED			
	2 PLACES ± 0.2	± ---	CGTAN	2008/07/25	MATERIAL NO. DOCUMENT NO. SHEET NO.				
	1 PLACE ± ---	± ---	APPROVED BY	DATE	SD-78443-001 6 OF 6				
	ANGULAR ± 1 °		SHLENI	2010/03/29	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE						
			SIZE	A3					